

# MOS FIELD EFFECT TRANSISTOR 2SK3712

## SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The 2SK3712 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for high voltage applications such as DC/DC converter.

#### **FEATURES**

- High voltage: VDSS = 250 V
- Gate voltage rating: ±30 V
- Low on-state resistance

 $R_{DS(on)}$  = 0.58  $\Omega$  MAX. (V<sub>GS</sub> = 10 V, I<sub>D</sub> = 4.5 A)

- Low Ciss: Ciss = 450 pF TYP. (VDS = 10 V, ID = 0 A)
- · Built-in gate protection diode
- TO-251/TO-252 package

#### ★ ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3712	TO-251 (MP-3)
2SK3712-Z	TO-252 (MP-3Z)

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

	,		
Drain to Source Voltage (V <sub>GS</sub> = 0 V)	VDSS	250	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±30	V
Drain Current (DC) (Tc = 25°C)	$I_{D(DC)}$	±9.0	Α
Drain Current (pulse) Note1	I <sub>D(pulse)</sub>	±27	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	40	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	Рт2	1.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	9	Α
Single Avalanche Energy Note2	Eas	8.1	mJ
Repetitive Avalanche Current Note3	lar	9	Α
Repetitive Pulse Avalanche Energy Note3	Ear	8.1	mJ

(TO-251)



(TO-252)



- **Notes 1.** PW  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1%
  - **2.** Starting Tch = 25°C, VDD = 125 V, Rg = 25  $\Omega$ , Vgs = 20  $\rightarrow$  0 V, L = 100  $\mu$ H
  - **3.**  $T_{ch(peak)} \le 150^{\circ}C$ , L = 100  $\mu$ H

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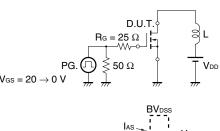


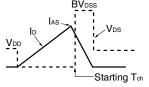
### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

v.DataSheeCHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate Leakage Current	Igss	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V			±10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.5	3.5	4.5	٧
Forward Transfer Admittance Note	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4.5 A	3	6		S
Drain to Source On-state Resistance Note	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.5 A		0.45	0.58	Ω
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		450		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V		100		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		40		pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 125 V, I <sub>D</sub> = 4.5 A		8		ns
Rise Time	tr	V <sub>GS</sub> = 10 V		8		ns
Turn-off Delay Time	td(off)	$R_G = 0 \Omega$		21		ns
Fall Time	t <sub>f</sub>			6		ns
Total Gate Charge	QG	V <sub>DD</sub> = 200 V		14		nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = 10 V		3		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 9.0 A		7		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 9 A, V <sub>GS</sub> = 0 V		0.9	1.5	V
Reverse Recovery Time	trr	I <sub>F</sub> = 9 A, V <sub>GS</sub> = 0 V		150		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		630		nC

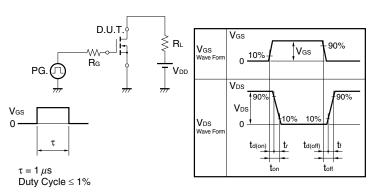
Note Pulsed

### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

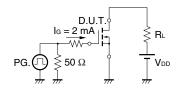




### **TEST CIRCUIT 2 SWITCHING TIME**



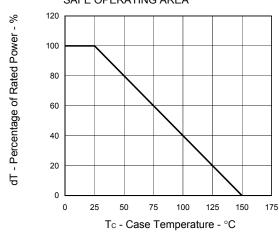
### **TEST CIRCUIT 3 GATE CHARGE**



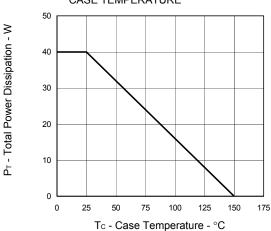


### TYPICAL CHARACTERISTICS (TA = 25°C)

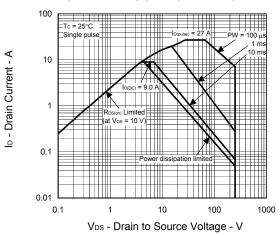
### www.DataShee DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



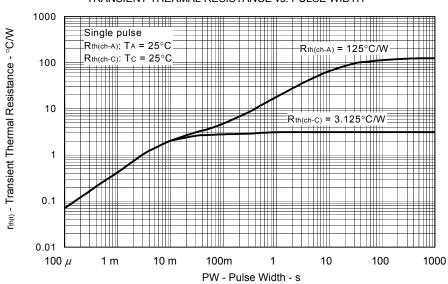
### TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



#### FORWARD BIAS SAFE OPERATING AREA

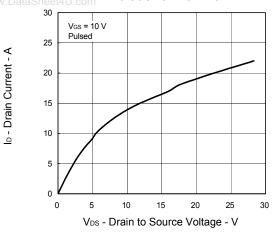


### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

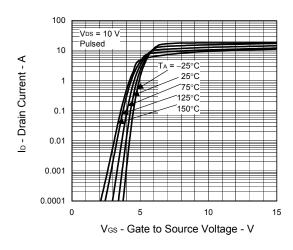




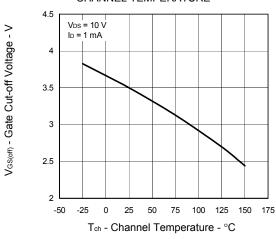
### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



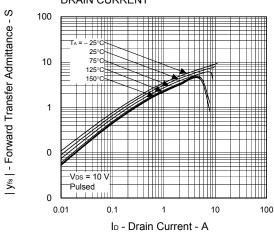
### FORWARD TRANSFER CHARACTERISTICS



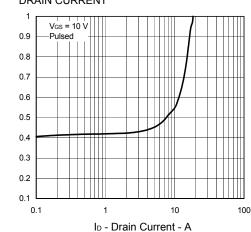
### GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



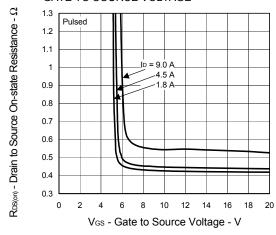
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



### DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



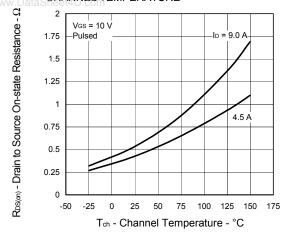
### DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



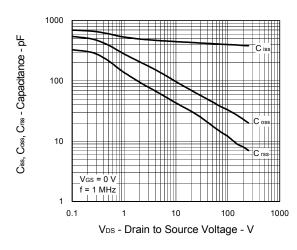
 $R_{DS(cm)}$  - Drain to Source On-state Resistance -  $\Omega$ 



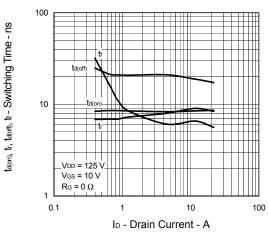
### DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



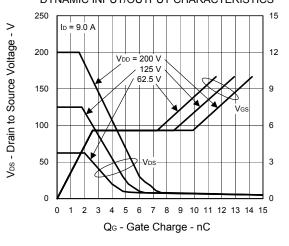
### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



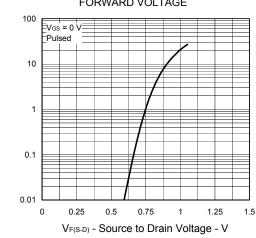
SWITCHING CHARACTERISTICS



DYNAMIC INPUT/OUTPUT CHARACTERISTICS

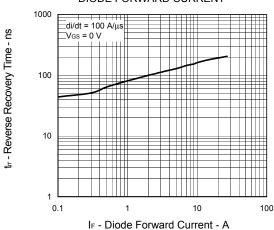


SOURCE TO DRAIN DIODE FORWARD VOLTAGE



IF - Diode Forward Current - A

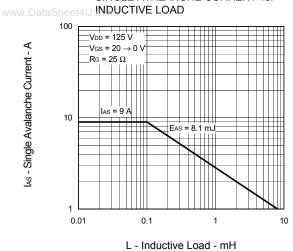
REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



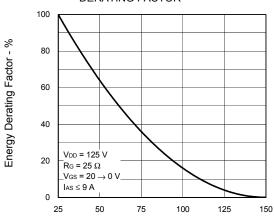
Ves - Gate to Source Voltage - V



### SINGLE AVALANCHE CURRENT vs.



### SINGLE AVALANCHE ENERGY **DERATING FACTOR**

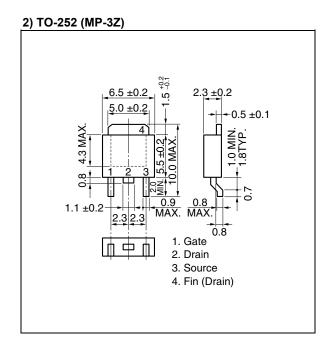


Starting  $T_{\text{ch}}$  - Starting Channel Temperature -  $^{\circ}\text{C}$ 

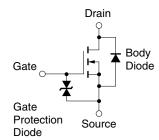


### **★ PACKAGE DRAWINGS (Unit: mm)**

1) TO-251 (MP-3) 6.5 ±0.2 2.3 ±0.2  $5.0 \pm 0.2$ 0.5 ±0.1  $1.6 \pm 0.2$ ģ. 5.5 Σ 13.7 O MIN. 1.1 ±0.2 0.5 +0.2 0.5 +0.2 1. Gate 2. Drain 3. Source 4. Fin (Drain)



### **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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